

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	METHOD AND STRUCTURE FOR IMPROVING CMOS DEVICE RELIABILITY USING COMBINATIONS OF INSULATING MATERIALS
Application Type :	regular, utility
Attorney Docket Number :	FIS920040194US1
Correspondence address:	
Customer Number:	29371
	
Inventors Information:	
<u>Inventor 1:</u>	
Applicant Authority Type:	Inventor
Citizenship:	CN
Given Name:	Haining
Family Name:	Yang
Residence:	
City of Residence:	Wappingers Falls
State of Residence:	NY
Country of Residence:	US
Address-1 of Mailing Address:	36 Robinson Lane
Address-2 of Mailing Address:	
City of Mailing Address:	Wappingers Falls
State of Mailing Address:	NY
Postal Code of Mailing Address:	12590
Country of Mailing Address:	US
Phone:	
Fax:	
E-mail:	
<u>Inventor 2:</u>	
Applicant Authority Type:	Inventor
Citizenship:	SG
Given Name:	Eng
Middle Name:	Hua
Family Name:	Lim

Residence:

City of Residence: Singapore
Country of Residence: SG
Address-1 of Mailing Address: Blk. 521, Bedok North, Avenue 1
Address-2 of Mailing Address: #06-280
City of Mailing Address: Singapore
State of Mailing Address:
Postal Code of Mailing Address: 460521
Country of Mailing Address: SG
Phone:
Fax:
E-mail:

Assignee 1:

Organization Name: International Business Machines Corporation
Address-1 of Mailing Address: New Orchard Road
Address-2 of Mailing Address:
City of Mailing Address: Armonk
State of Mailing Address: NY
Postal Code of Mailing Address: 10504
Country of Mailing Address: US
Phone:
Fax:
E-mail: